



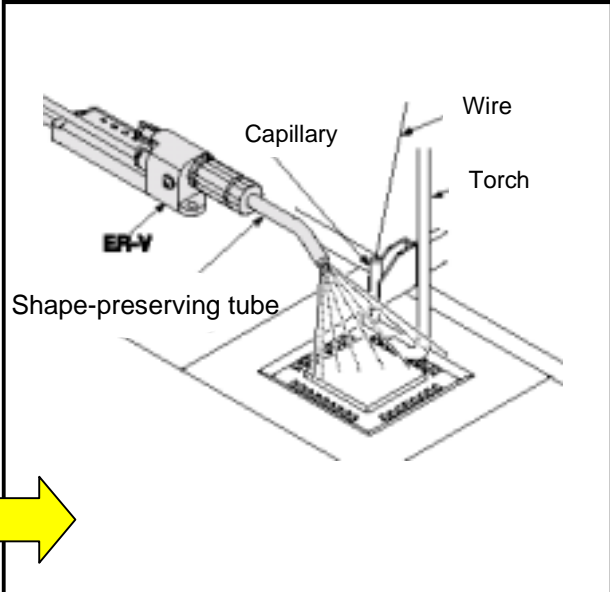
# Removing charges/ dust in wire bonding

## OUTLINE / PREVIOUS

**Customer: Semiconductor equipment manufacturer**  
**Process: Wire bonding process**  
 Charge/ dust are to be removed in the process of bonding terminal on chip and inner lead of lead frame.

**PROBLEM**  
 Frictional charge with wire, clog with particles (ultrafine particle) in capillary are required to be prevented.

## SOLUTION



**MODEL / HOW TO**  
**ER-VS01 ER-VAJK ER-VAK10**  
 Install nozzle head close to the object. Pinpoint and effective static removal is possible.

### BENEFIT 1 Shape-preserving tube

A shape-preserving tube **ER-VAK10** (tube length: 112 mm) can be bent easily and its shape is kept, which requires no fixing of the tube. We also have **ER-VAK30** (tube length: 312 mm) and **ER-VAK50** (tube length: 512 mm).

### BENEFIT 2 Discharge halt input

**ER-VS01** can operate to turn ON/ OFF of discharge with input signals from external device. Sensors can be used to detect the objects so that the ion air is generated only when required.

### BENEFIT 3 Discharge indicator incorporated

ON/ OFF status of discharge can be visually confirmed with LED indicator. Discharging stopped while power is ON. - such troubles can be prevented from happening.

